

TYN640/TYN840 Series

- Description:**

High current density due to singel mesa trchnology;

- Applications:**

TYN640/TYN840 series of silicon controlled rectifiers are specifically designed for medium power switching and phase control applications.

TYN640/TYN840 series are suitable for general purpose applications,a high gate sensitivity is required.

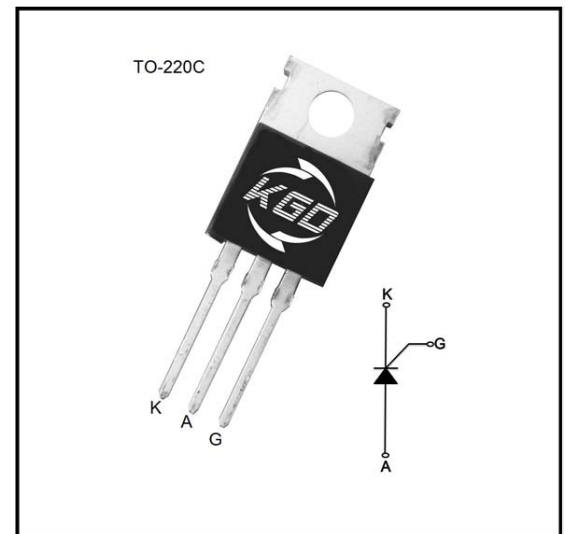
- Features:**

Blocking voltage to 600 to 800V

On-state RMS current to 40A

Non-repetitive peak on-state current to 460A

- Absolute Maximum Ratings**



Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	Repetitive peak off-state voltage	$T_J=25^\circ\text{C}$	600	800	V
V_{RRM}	Repetitive peak Reverse voltage	$T_J=25^\circ\text{C}$	600	800	V
$I_{T(RMS)}$	RMS on-state current (all conduction angels)	$T_c=95^\circ\text{C}$	-	40	A
$I_{T(av)}$	Average on-state current (half sine wave)	$T_c=95^\circ\text{C}$	-	25	A
I_{TSM}	Non repetitive surge peak on-state current (half sine cycle, $T_J=25^\circ\text{C}$)	$f=50\text{Hz}$ $t=10\text{ms}$	-	460	A
		$f=50\text{Hz}$ $t=8.3\text{ms}$	-	490	
I^2t	I^2t Value for fusing	$t_p=10\text{ms}$	-	1060	A^2S
di_T/dt	Repetitive rate of rise of on-state current after triggering $I_{TM}=20\text{A}$ $I_G=50\text{mA}$ di_G/dt 50mA/ms		-	50	A/ μs
I_{GM}	Peak gate current	$T_p=20\mu\text{s}$, $T_J=125^\circ\text{C}$	-	4	A
P_{GM}	Peak gate power		-	5	W
$P_{G(AV)}$	Average gate power dissipation	$T_J=125^\circ\text{C}$	-	1	W
T_{STG}	Storage junction temperature range		-40	150	$^\circ\text{C}$
T_J	Operrating junction temperature range		-40	125	$^\circ\text{C}$

TYN640/TYN840 Series
● Electrical Characteristics

Symbol	Conditions	TYN640/TYN840			Unit
		MIN.	TYP.	MAX.	
I_{GT}	$V_D=12V$ $R_L=33\Omega$	5	15	35	mA
V_{GT}		-	0.8	1.5	V
V_{GD}	$V_D=V_{DRM}$, $R_L=3.3K\Omega$, $T_J=125^\circ C$	-	-	0.2	V
I_L	$I_T=1.2I_{GT}$	-	60	150	mA
I_H	Holding current	-	20	75	mA
dv/dt	$V_{DM}=67\%V_{DRM}$, gate open, $T_J=125^\circ C$	1000	-	-	V/ μs

● Electrical Characteristics

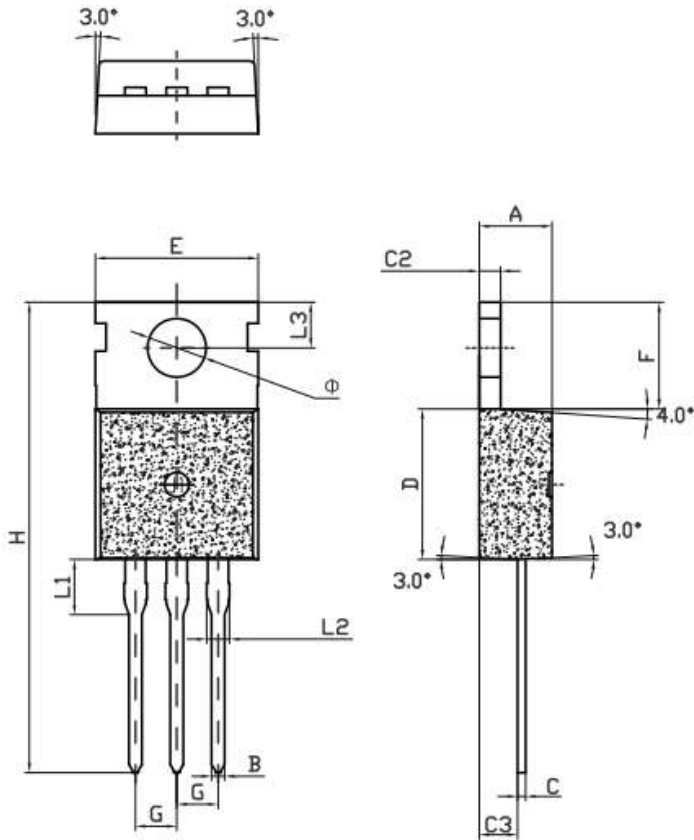
Symbol	Parameter	Numerical(MAX)	Unit
V_{TM}	$I_T=80A$, $t_p=380\mu s$ $T_J=25^\circ C$	1.8	V
I_{DRM}	$V_D=V_{DRM}$, $V_R=V_{RRM}$ $T_J=25^\circ C$	10	μA
I_{RRM}	$T_J=125^\circ C$	4	mA

● Thermal Characteristics

Symbol	Parameter	Numerical(MAX)	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	0.78	$^\circ C/W$

TYN640/TYN840 Series

● Package Outline Dimensions

TO-220C


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.4		4.6	0.173		1.181
B	0.7		0.9	0.027		0.035
C	0.45		0.6	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.2		2.6	0.086		0.102
D	8.9		9.9	0.350		0.390
E	9.9		10.3	0.390		0.406
F	6.3		6.9	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	11.0		11.7
L1		3.2			0.126	
L2	1.14		1.7	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

TYN640/TYN840 Series

FIG.1: Maximum power dissipation versus average on-state current(half cycle)

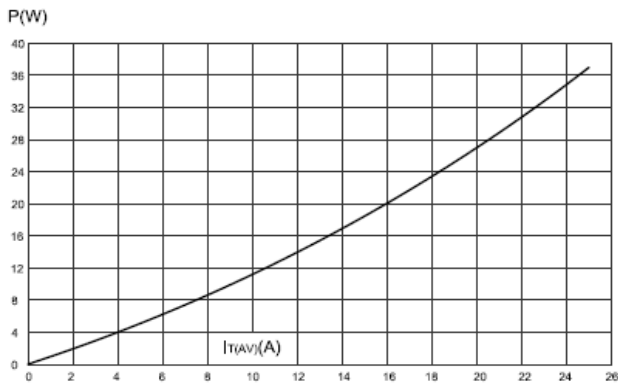


FIG.2: RMS on-state current versus case temperature(full cycle)

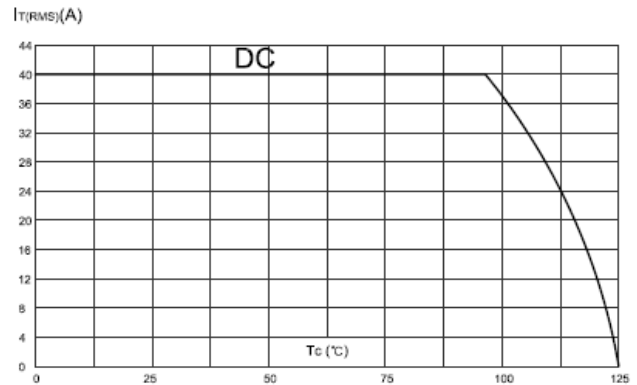


FIG.3: On-state characteristics (maximum values).

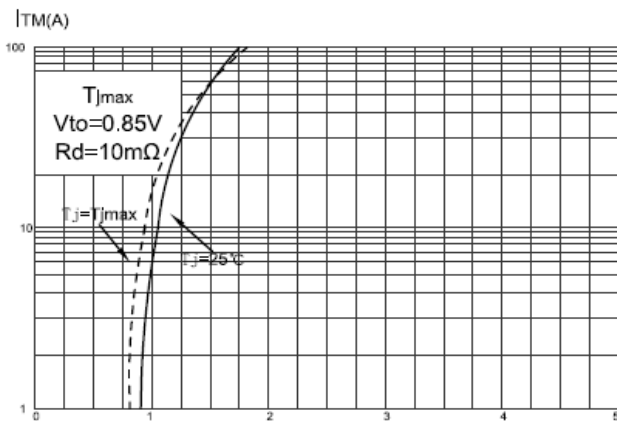


FIG.4: Surge peak on-state current versus number of cycles.

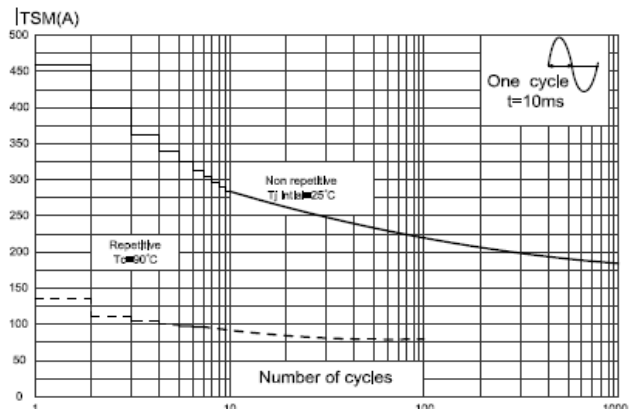


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ms}$, and corresponding value of I^2t .

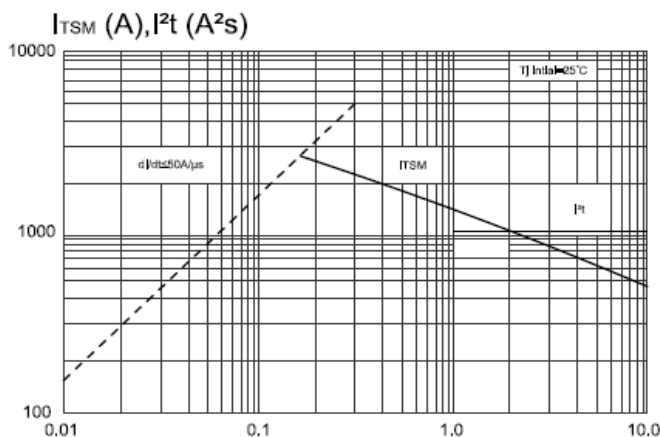


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature (typical values)

